TOSHIBA BI-DIRECTIONAL TRIODE THYRISTOR SILICON PLANAR TYPE

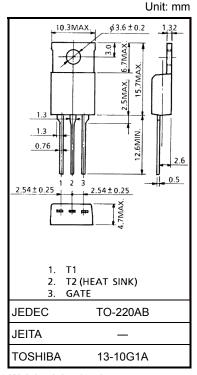
# SM6G45, SM6J45, SM6G45A, SM6J45A

#### AC POWER CONTROL APPLICATIONS

- Repetitive Peak Off-State Voltage: VDRM = 400V, 600V
- R.M.S On-State Current: IT (RMS) = 6A
- High Commutating (dv / dt)

### **ABSOLUTE MAXIMUM RATINGS**

CHARACTERI	STIC	SYMBOL	RATING	UNIT	
Repetitive Peak Off-	SM6G45 SM6G45A	V	400	<b>&gt;</b>	
State Voltage	SM6J45 SM6J45A	$V_{DRM}$	600		
R.M.S On-State Curren (Full Sine Waveform Tc	•	I <sub>T (RMS)</sub>	6	Α	
Peak One Cycle Surge	On-State		60 (50Hz)	Α	
Current (Non-Repetitive)		ITSM	66 (60Hz)	A	
I <sup>2</sup> t Limit Value		I <sup>2</sup> t	18	A <sup>2</sup> s	
Critical Rate of Rise of C Current	On-State	di / dt	50	A / μs	
Peak Gate Power Dissip	ation	P <sub>GM</sub>	5	W	
Average Gate Power Dis	ssipation	P <sub>G (AV)</sub>	0.5	W	
Peak Gate Voltage		$V_{GM}$	10	V	
Peak Gate Current		I <sub>GM</sub>	2	Α	
Junction Temperature		Tj	-40~125	°C	
Storage Temperature Ra	ange	T <sub>stg</sub>	-40~125	°C	



Weight: 2.0 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

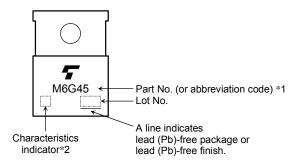
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).



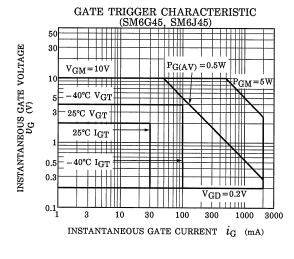
## **ELECTRICAL CHARACTERISTICS (Ta = 25°C)**

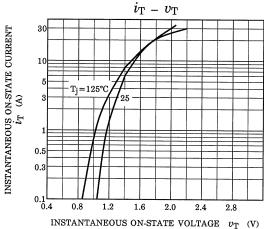
CHARACTERISTIC		SYMBOL	TEST CONDITION		MIN	TYP.	MAX	UNIT		
Repetitive Peak Off-State Current		I <sub>DRM</sub>	V <sub>DRM</sub> = Rated, T <sub>j</sub> = 125°C		_	_	2	mA		
Gate Trigger Voltage			I	V <sub>GT</sub>	V <sub>D</sub> = 12V R <sub>L</sub> = 20Ω	T2 (+), Gate (+)	_	_	2	· · · · · ·
	SM6G4	5	II			T2 (+), Gate (-)	_	_	2	
	SM6J45	5	III			T2 (-), Gate (-)	_	_	2	
			IV			T2 (-), Gate (+)	_	_	_	
			I			T2 (+), Gate (+)	_	_	1.5	
	SM6G4	5A	II			T2 (+), Gate (-)	_	_	1.5	
	SM6J45	iΑ	III			T2 (-), Gate (-)	_	_	1.5	
			IV			T2 (-), Gate (+)	_	_	_	
Gate Trigger Current			ı	I <sub>GT</sub>	V <sub>D</sub> = 12V R <sub>L</sub> = 20Ω	T2 (+), Gate (+)	_	_	30	mA
	SM6G4	5	II			T2 (+), Gate (-)	_	_	30	
	SM6J45	5	III			T2 (-), Gate (-)	_	_	30	
			IV			T2 (-), Gate (+)	_	_	_	
			I			T2 (+), Gate (+)	_	_	20	
	SM6G4	5A	II			T2 (+), Gate (-)	_	_	20	
	SM6J45	iΑ	III			T2 (-), Gate (-)	_	_	20	
				Ţ		T2 (-), Gate (+)	_	_	_	
Peak On-State Voltage		V <sub>TM</sub>	I <sub>TM</sub> = 9A		_	_	1.5	V		
Gate Non-Trigger Voltage		V <sub>GD</sub>	V <sub>D</sub> = Rated, Tc = 125°C		0.2	_	_	V		
Holding Current		lΗ	V <sub>D</sub> = 12V, I <sub>TM</sub> = 1A		_	_	50	mA		
Thermal Resistance		R <sub>th (j-c)</sub>	Junction to Case, AC		_	_	2.5	°C/W		
Critical Rate of SM6G45 Rise of Off-State Voltage at Commutation SM6J45  SM6G45A SM6J45A			(dv / dt) c	V <sub>DRM</sub> = 400V, (di / dt) c = -3.3A / ms		10	_	_	V / µs	
				(uv / ut) C	$T_j = 125^{\circ}C$		4	_	_	v / μs

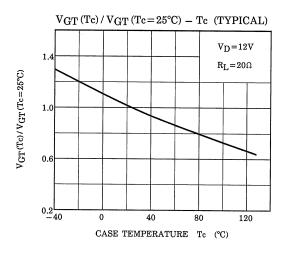
### **MARKING**

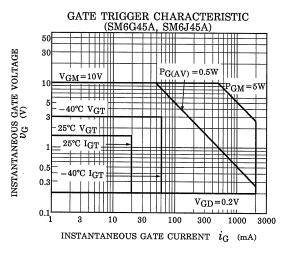


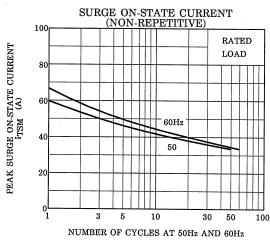
	Part No. (or abbreviation code)	Part No.
*1	M6G45	SM6G45, SM6G45A
	M6J45	SM6J45, SM6J45A
*2	Nothing	SM6G45, SM6J45
	Α	SM6G45A, SM6J45A

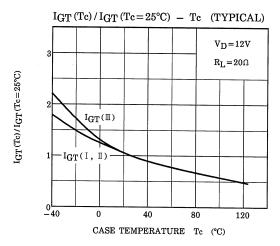


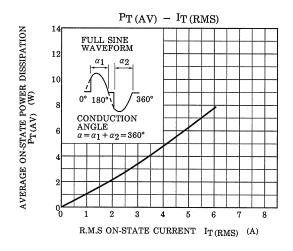


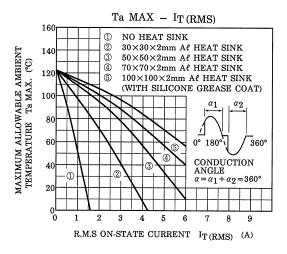


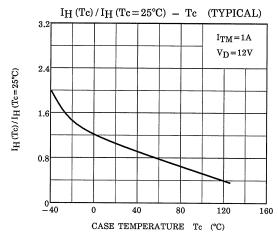


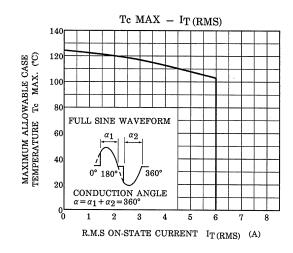


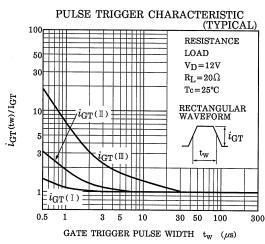


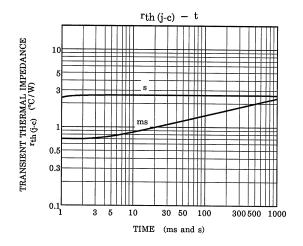












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